



8/Amdt B
P. Walker
4-1-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	Docket Number: 96-0841.01
Akram)	Paper No.: 7
Serial No: 09/733,418)	Art Unit: 2815
Filed: 12/08/00)	Examiner: Brock II, P.
For: DEVICE ISOLATION FOR SEMICONDUCTOR DEVICES)	

Commissioner for Patents
Washington, D.C. 20231

Certificate of Mailing (37 C.F.R. §1.8)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date below:

03/15/02 Peggy Loyd-Foster
Date Signature

Dear Commissioner:

REPLY AND AMENDMENT UNDER 37 CFR §1.116

This paper is in response to outstanding Office Action dated 10/18/01 and designated as paper no. 6.

In the Claims:

Please cancel claim 44, without prejudice.

Please amend claims 25, 26, 34, 35, 40, 41, 50 and 51, as indicated below.

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25. (Amended) A process for forming device isolation for a semiconductor assembly, said process comprising the steps of:

Micron Technology, Inc.

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